

Product Summary

$V_{(BR)SSS}$	$R_{SS(on)MAX}$	I_s
12V	2.75mΩ@4.5V	13A
	6.1mΩ@2.5V	

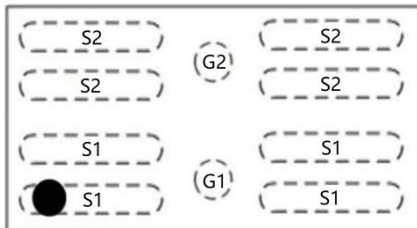
Feature

- Trench MOSFET Technology
- Extremely low $R_{SS(on)}$
- ESD Protected

Application

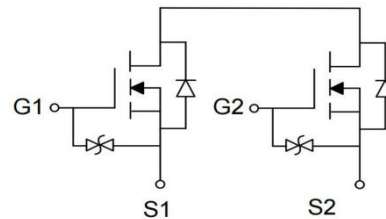
- Battery Protection

Package

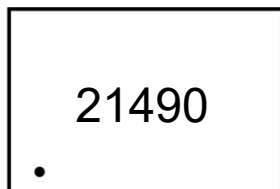


WLCSP-10L

Circuit diagram



Marking



Absolute maximum ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Source-Source Voltage	V_{SS}	12	V
Gate-Source Voltage	V_{GS}	± 8	V
Continuous Source Current ¹⁾ ($T_C=25^{\circ}\text{C}$)	I_S	13	A
Continuous Source Current ($T_C=100^{\circ}\text{C}$)	$I_S(100^{\circ}\text{C})$	10	A
Pulsed Source Current ²⁾	I_{SM}	52	A
Power Dissipation ($T_C=25^{\circ}\text{C}$)	P_D	0.5	W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	250	$^{\circ}\text{C}/\text{W}$
Junction Temperature	T_J	150	$^{\circ}\text{C}$
Storage Temperature	T_{STG}	-55 ~ +150	$^{\circ}\text{C}$

Electrical characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Source-source breakdown voltage	$V_{(BR)SSS}$	$V_{GS} = 0\text{V}, I_S = 250\mu\text{A}$	12			V
Zero gate voltage source current	I_{SSS}	$V_{SS} = 12\text{V}, V_{GS} = 0\text{V},$			1	μA
Gate-body leakage current	I_{GSS}	$V_{GS} = \pm 8\text{V}, V_{SS} = 0\text{V}$			± 10	μA
Gate threshold voltage	$V_{GS(th)}$	$V_{SS} = 0\text{V}, V_{GS}, I_S = 1\text{mA}$	0.55	0.95	1.35	V
Source-source on-resistance	$R_{SS(on)}$	$V_{GS} = 4.5\text{V}, I_S = 6\text{A}$		2.1	2.75	m Ω
		$V_{GS} = 3.8\text{V}, I_S = 6\text{A}$		2.2	2.85	
		$V_{GS} = 3.1\text{V}, I_S = 6\text{A}$		2.4	3.95	
		$V_{GS} = 2.5\text{V}, I_S = 6\text{A}$		3.1	6.1	
Dynamic characteristics³⁾						
Input Capacitance	C_{iss}	$V_{SS} = 0\text{V}, V_{GS} = 8\text{V}, f = 1\text{MHz}$		3500		pF
Output Capacitance	C_{oss}			450		
Reverse Transfer Capacitance	C_{rss}			400		
Total Gate Charge	Q_g	$V_{SS} = 6\text{V}, V_{GS} = 4.5\text{V}, I_S = 4\text{A}$		23		nC
Gate-Source Charge	Q_{gs}			11		
Gate-Drain Charge	Q_{gd}			5		
Gate Resistance	R_g	$f = 1\text{MHz}$		620		Ω
Turn-on delay time	$t_{d(on)}$	$V_{SS} = 6\text{V}, V_{GS} = 4.5\text{V},$ $R_L = 1.5\Omega, R_G = 3\Omega$		0.6		nS
Turn-on rise time	t_r			1.4		
Turn-off delay time	$t_{d(off)}$			6.6		
Turn-off fall time	t_f			4		
Source-Drain Diode characteristics						
Diode Forward voltage	V_{SS}	$V_{GS} = 0\text{V}, I_S = 4\text{A}$			1.2	V
Diode Forward current	I_S				13	A
Diode Pulsed Forward current ¹⁾	I_{SM}				52	A

Notes:

- 1) Continuous current based on $R_{\theta JA}$
- 2) Repetitive Rating: Pulse width limited by maximum junction temperature $R_G=25\text{ohm}, L=0.5\text{mH}, I_{AS}=35\text{A}$
- 3) Guaranteed by design, not subject to production.

Typical Characteristics

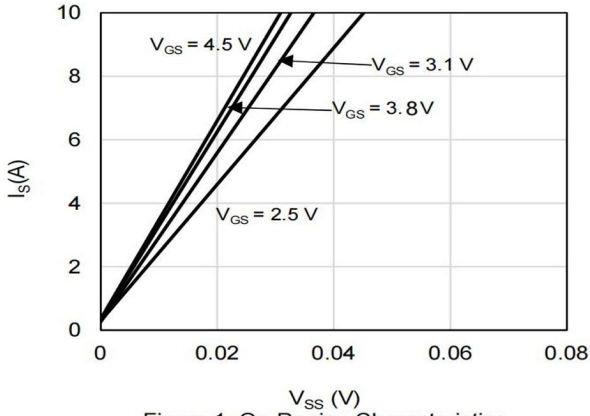


Figure 1: On-Region Characteristics

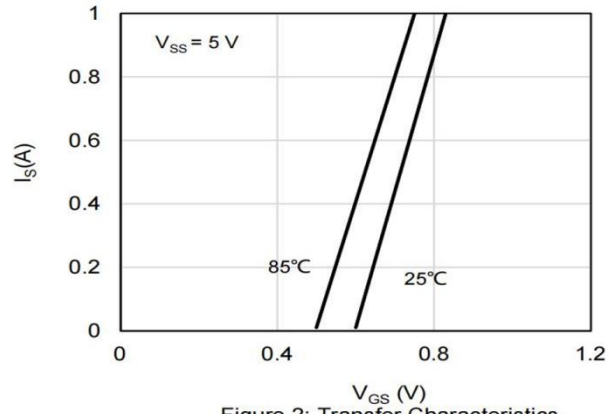


Figure 2: Transfer Characteristics

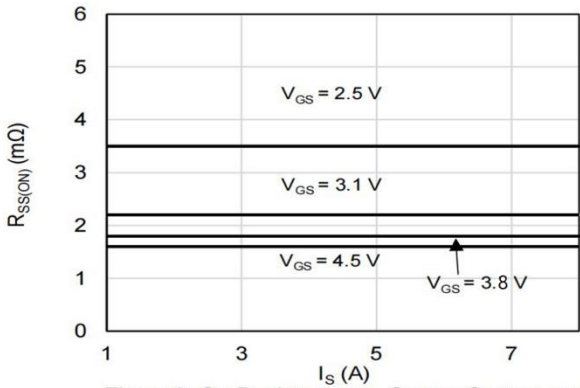


Figure 3: On-Resistance vs. Source Current and Gate Voltage

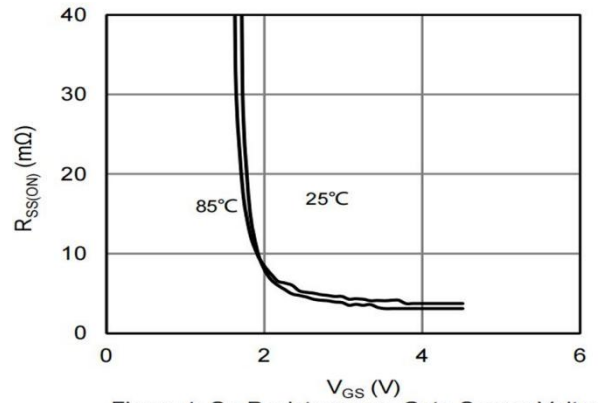


Figure 4: On-Resistance vs. Gate-Source Voltage

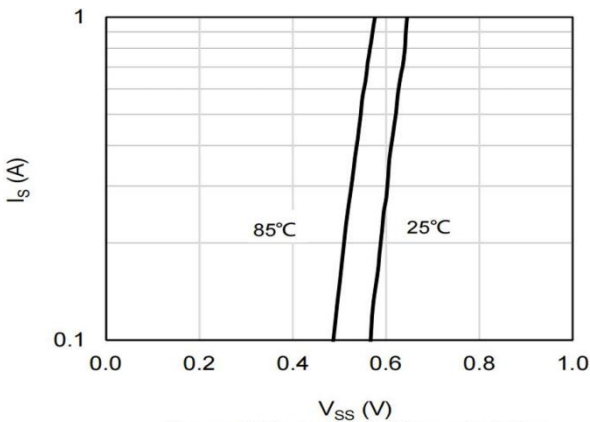


Figure 5: Body-Diode Characteristics

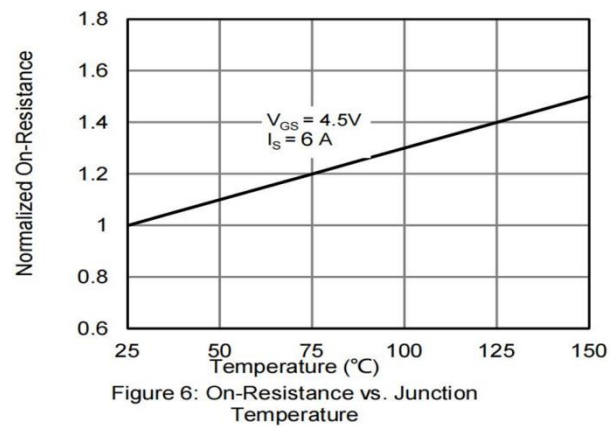


Figure 6: On-Resistance vs. Junction Temperature

Typical Characteristics

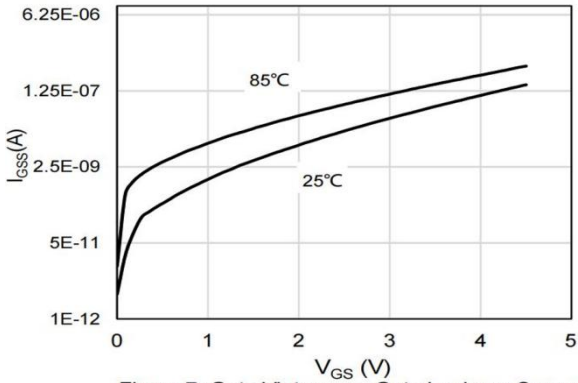


Figure 7: Gate Voltage vs. Gate Leakage Current

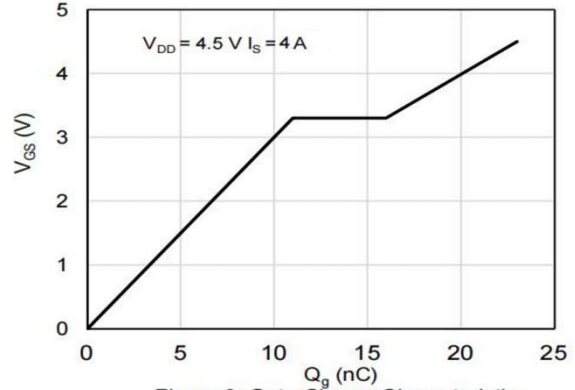


Figure 8: Gate-Charge Characteristics

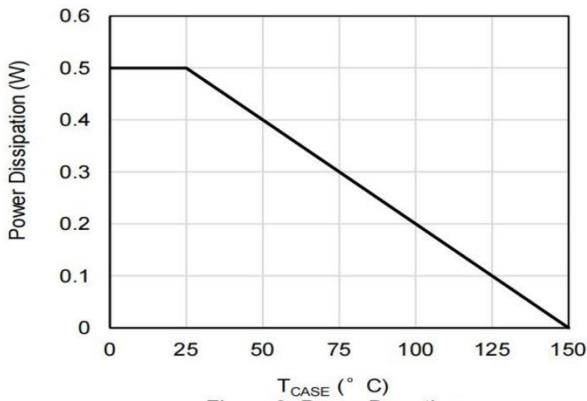


Figure 9: Power De-rating

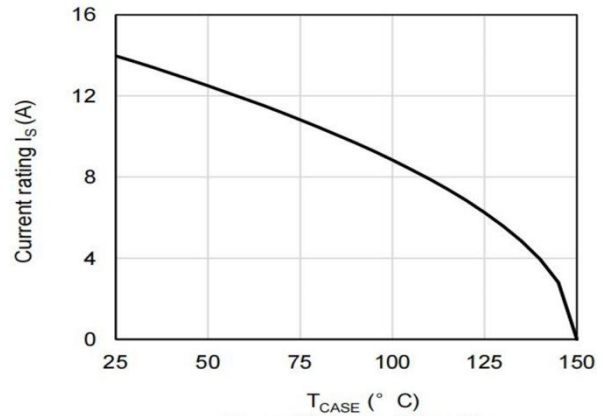


Figure 10: Current De-rating

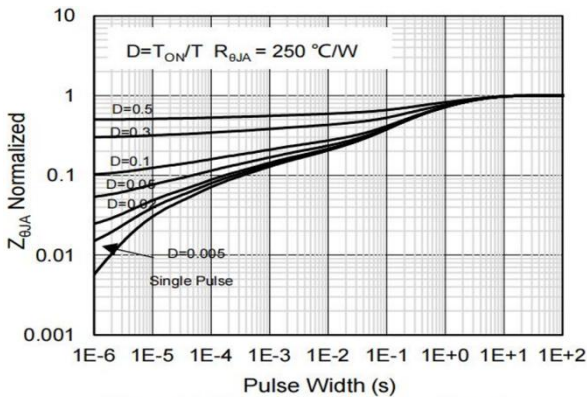


Figure 13: Normalized Maximum Transient Thermal Impedance

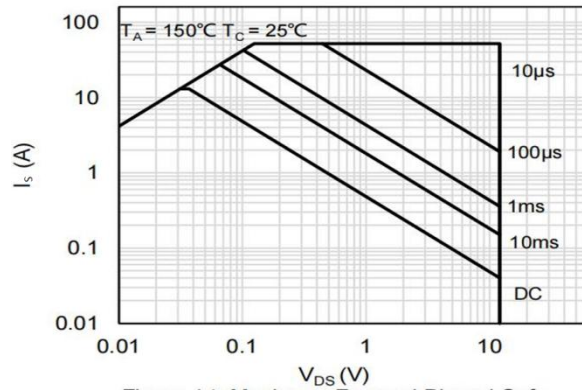
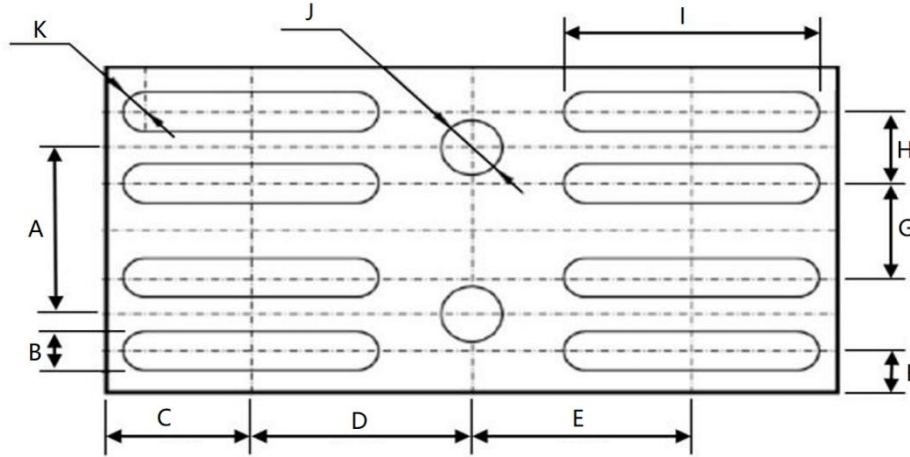


Figure 14: Maximum Forward Biased Safe Operating Area

WLCSP-10L Package Information

Bottom View



Side View



SYMBOL	DIMENSIONS	
	MILLIMETERS	INCHES
A	0.750	0.030
B	0.175	0.007
C	0.605	0.024
D	0.895	0.035
E	0.895	0.035
F	0.218	0.009
G	0.425	0.017
H	0.325	0.013
I	1.040	0.041
J	0.250	0.010
K	0.088	0.003
L	0.100	0.004